

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	9220	(probe probing testing) with (tetragon elliptical circle circular chamfer chamfered)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:59
L2	59	(resistor resistive) same 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:28
L3	1070	(resistor resistive) and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:58
L4	514	3 and (glass resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:29
L5	1868111	substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:29
L6	353	5 and 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:30
L7	307	(conductor trace wiring) and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:58
L8	68	(solder paste) and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:57
L9	12013	case with (insulation insulating insulated) with (carrier substrate board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:57

L10	2302	(resistor resistive) and 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:58
L11	657103	(conductor trace wiring) and "11"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:58
L12	1406	(conductor trace wiring) and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:58
L13	190	(probe probing testing) and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:59
L14	66	13 and (tetragon elliptical circle circular chamfer chamfered)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:59

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	429832	electronic with device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:56
L2	186737	case and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:57
L3	187277	(encase case) and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:57
L4	272119	(insulating insulated) with (substrate carrier board pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:58
L5	15572	3 and 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:58
L6	5553	5 and ((mount mounting mounted creisstor capacitor) with substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:59
L7	605	(probing probe probed) and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 12:00
L8	417962	(overcoat coating coated coating) with (glass resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 12:00
L9	596	7 and "8"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 12:00

L10	120	7 and 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 12:00
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